

## 450 kHz, High Accuracy Current Sensor With Zero Current Voltage Reference in SOIC-6 Package

### FEATURES AND BENEFITS

- High operating bandwidth and fast response time
  - 450 kHz bandwidth
  - 1.3  $\mu$ s response time
- High-accuracy current measurements
  - $\pm 1.5\%$  sensitivity error over temperature
  - $\pm 4$  mV offset voltage over temperature
  - Nonratiometric operation with VREF output for enhanced accuracy in noisy environments
  - Differential sensing robust against external magnetic fields
  - Magnetic hysteresis-free operation
- Wide operating temperature,  $-40^{\circ}\text{C}$  to  $150^{\circ}\text{C}$
- Low internal primary conductor resistance (0.68 m $\Omega$ ) for better power efficiency (low dissipation)
- Highly isolated compact surface-mount package
  - 3500  $V_{\text{RMS}}$  rated isolation voltage
  - 840  $V_{\text{RMS}}$  / 1188  $V_{\text{DC}}$  basic isolation voltages
  - 420  $V_{\text{RMS}}$  / 594  $V_{\text{DC}}$  reinforced isolation voltages

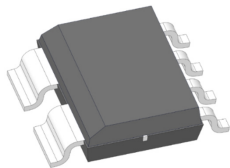
### DESCRIPTION

The ACS37010 is a fully integrated current sensor IC that senses current flowing through the compact SOIC LZ package. The current conductor has a very low 0.68 m $\Omega$  resistance, ideal for low power dissipation constraints. The sensor is factory-trimmed to provide high accuracy over the entire operating range without the need for customer programming.

The internal construction provides high isolation and excellent magnetic coupling of the field generated by the current flowing in the conductor and the fully monolithic Hall sensor IC. The current is sensed differentially by two Hall plates that subtract interfering common-mode magnetic fields. The sensor provides a very fast 1.3  $\mu$ s response time analog output with VREF pin for use in noisy supply environments. The IC has no physical connection to the integrated current conductor and provides 3500  $V_{\text{RMS}}$  of isolation between the primary and secondary signal leads of the package. This rating provides basic working voltage of 840  $V_{\text{RMS}}$  and reinforced working voltage of 420  $V_{\text{RMS}}$ .

The ACS37010 is in a custom 6-pin SOIC package (suffix LZ). Devices are RoHS-compliant and lead (Pb) free without the use of RoHS exemptions with 100% matte-tin-plated leadframes.

### PACKAGE:



Custom 6-pin SOIC  
(suffix LZ)

*Not to scale*

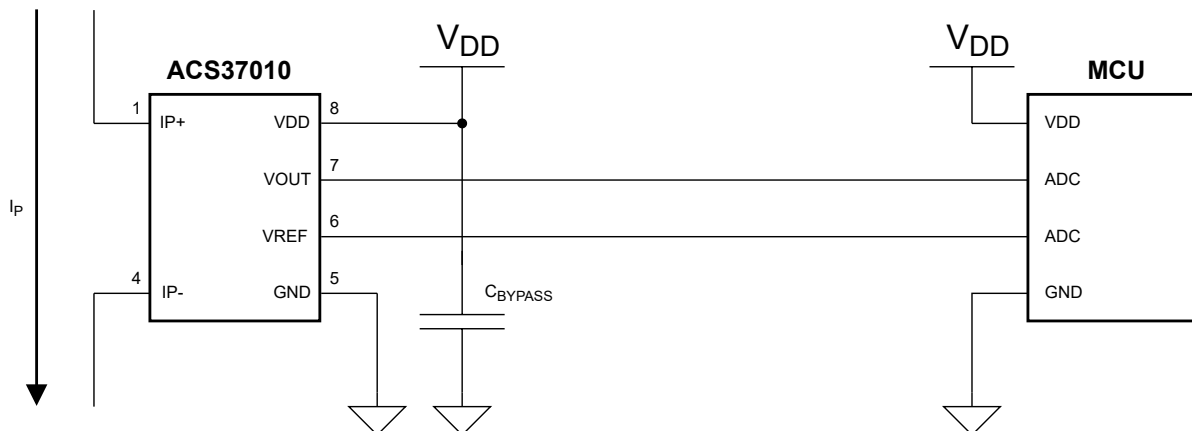


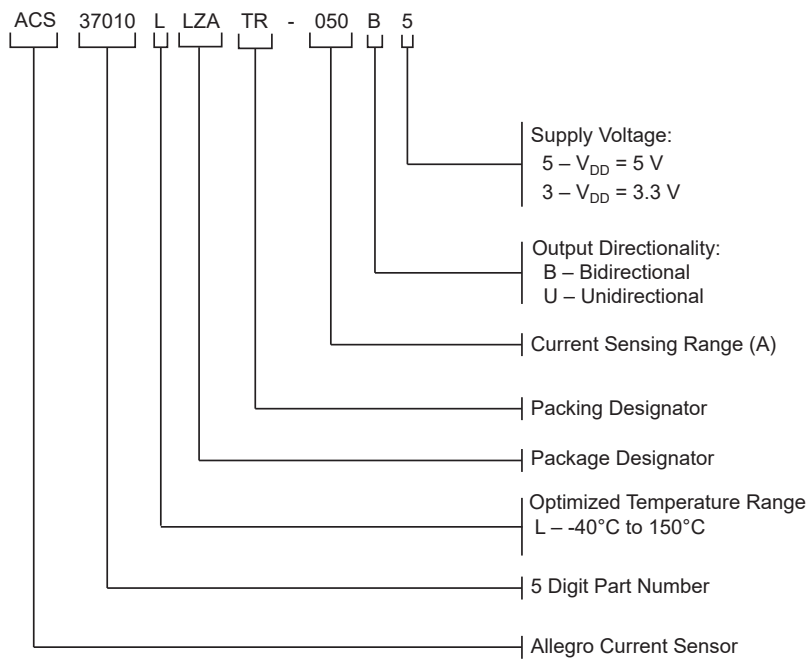
Figure 1: Typical Application Circuit

# ACS37010

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### SELECTION GUIDE

Part Number	Current Sensing Range, $I_{PR}$ (A)	Sensitivity (mV/A)	$V_{DD}$ (V)	$V_{QVO}$ (V)	Optimized Temperature Range, $T_A$ (°C)	Packing
ACS37010LLZATR-050B5	±50	40	5	2.5	-40 to 150	Tape and Reel, 3000 pieces per reel
ACS37010LLZATR-050B3	±50	26.4	3.3	1.65		



### ABSOLUTE MAXIMUM RATINGS

Characteristic	Symbol	Notes	Min.	Max.	Unit
Supply Voltage	$V_{DD}$		-0.5	6.5	V
Output Voltage	$V_O$	Applies to $V_{OUT}$ , $V_{REF}$	-0.5	$(V_{DD} + 0.7) \leq 6.5$	V
Operating Ambient Temperature	$T_A$		-40	150	°C
Storage Temperature	$T_{STG}$		-65	165	°C
Maximum Junction Temperature	$T_{J(max)}$		-	165	°C

### ISOLATION CHARACTERISTICS

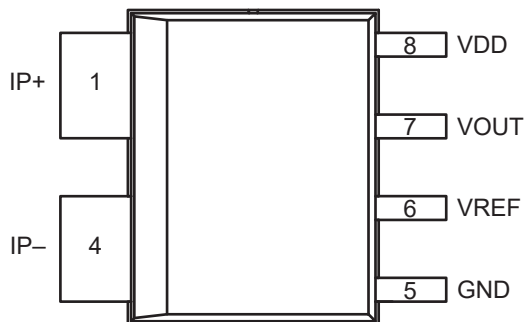
Characteristic	Symbol	Notes	Value	Units
Dielectric Strength [1][2]	$V_{ISO}$	Agency rated for 60 seconds per UL 62368 Edition 3	3500	$V_{RMS}$
Impulse Withstand	$V_{IMPULSE}$	Tested $\pm 5$ pulses at 2/minute in compliance to IEC 61000-4-5, 1.2 $\mu s$ (rise) / 50 $\mu s$ (width)	5000	$V_{PK}$
Working Voltage for Basic Isolation [2]	$V_{WVBI}$	Maximum approved working voltage for basic (single) isolation according to UL 62368 Edition 3	1188	$V_{PK}$ or $V_{DC}$
			840	$V_{RMS}$
Working Voltage for Reinforced Isolation [2]	$V_{WVRI}$	Maximum approved working voltage for reinforced isolation according to UL 62368 Edition 3	594	$V_{PK}$ or $V_{DC}$
			420	$V_{RMS}$
Clearance	$D_{CL}$	Minimum distance through air from IP leads to signal leads	4.2	mm
Creepage	$D_{CR}$	Minimum distance along package body from IP leads to signal leads	4.2	mm
Distance Through Insulation	DTI	Minimum internal distance through insulation	54	$\mu m$
Comparative Tracking Index	CTI	Material Group I	>600	V

[1] Production-tested for 1 second at 3150  $V_{RMS}$  in accordance with UL62368.

[2] Certification pending.

### PACKAGE CHARACTERISTICS

Characteristic	Symbol	Notes	Min.	Typ.	Max.	Unit
Internal Conductor Resistance	$R_{IC}$	$T_A = 25^\circ C$	-	0.68	-	m $\Omega$
Internal Conductor Inductance	$L_{IC}$	$T_A = 25^\circ C$	-	2.4	-	nH
Moisture Sensitivity Level	MSL	Per IPC/JEDEC J-STD-020	-	2	-	-



Package LZ, 6-Pin SOIC  
Pinout Diagram

### Terminal List Table

Number	Name	Description
1	IP+	Terminal for current being sensed
4	IP-	Terminal for current being sensed
5	GND	Device ground terminal
6	VREF	Zero current voltage reference
7	VOUT	Analog output representing the current flowing through IP
8	VDD	Device power supply terminal

### FUNCTIONAL BLOCK DIAGRAM

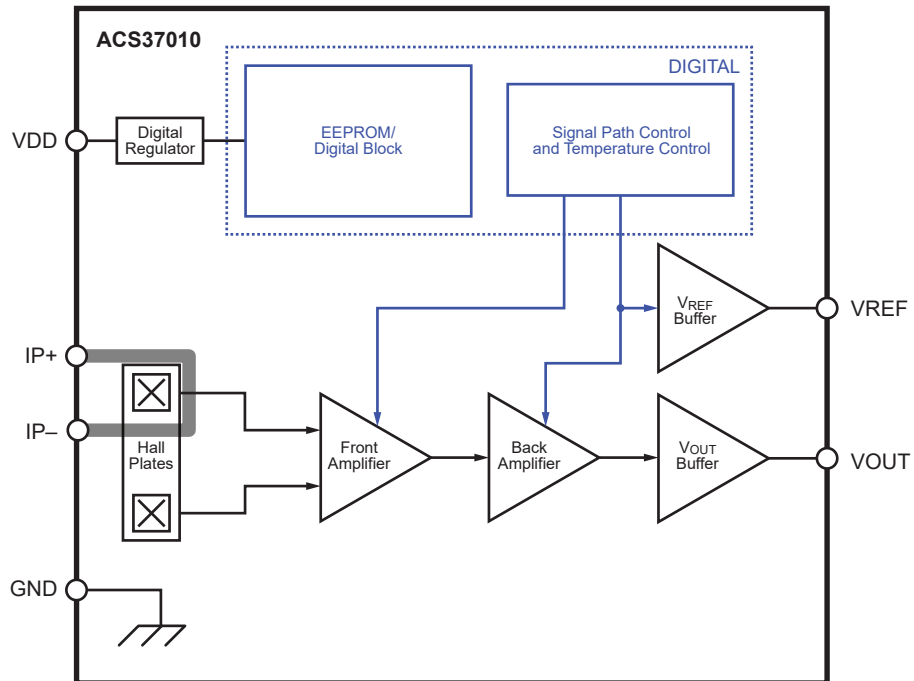


Figure 2: Functional Block Diagram

**COMMON ELECTRICAL CHARACTERISTICS:** Valid over full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $150^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 100\text{ nF}$ , and  $V_{\text{DD}} = 5\text{ V}$  or  $3.3\text{ V}$ , unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>GENERAL</b>						
Supply Voltage	$V_{\text{DD}}$	5 V variant	4.5	5	5.5	V
		3.3 V variant	3	3.3	3.6	V
Supply Current	$I_{\text{DD}}$	5 V variant, no load on VOUT or VREF	–	16	20	mA
		3.3 V variant, no load on VOUT or VREF	–	14	18	mA
VOUT Resistive Load	$R_{\text{L\_VOUT}}$	VOUT to GND, VOUT to VDD	10	–	–	k $\Omega$
VOUT Capacitive Load	$C_{\text{L\_VOUT}}$	VOUT to GND	–	1	6	nF
Supply Bypass Capacitor	$C_{\text{BYPASS}}$	VDD to GND	0.1	1	–	$\mu\text{F}$
Power-On Reset Release Voltage	$V_{\text{POR}}$	$V_{\text{DD}}$ rising 1 V/ms	2.7	2.9	3	V
Power-On Reset Hysteresis	$V_{\text{POR\_HYS}}$		250	300	500	mV
Power-On Time	$t_{\text{PO}}$	$T_A = 25^\circ\text{C}$	–	65	–	$\mu\text{s}$
Undervoltage Detection Threshold [1]	$V_{\text{UVD}}$	$T_A = 25^\circ\text{C}$ , VDD falling 1 V/ms	3.8	4.1	4.25	V
Undervoltage Detection Hysteresis [1]	$V_{\text{UVD\_HYS}}$		200	250	400	mV
Undervoltage Detection Time [1]	$t_{\text{UVD}}$	$V_{\text{DD}} < V_{\text{UVD}}$	–	70	200	$\mu\text{s}$
Undervoltage Detection Release Time [1]	$t_{\text{UVD\_R}}$	$V_{\text{DD}} > (V_{\text{UVD}} + V_{\text{UVD\_HYS}})$	–	6	–	$\mu\text{s}$
Overvoltage Detection Threshold	$V_{\text{OVD}}$	$T_A = 25^\circ\text{C}$ , VDD rising 1 V/ms	6.1	6.3	6.5	V
Overvoltage Detection Hysteresis	$V_{\text{OVD\_HYS}}$	$T_A = 25^\circ\text{C}$	400	500	600	mV
Overvoltage Detection Time	$t_{\text{OVD}}$	$V_{\text{DD}} > V_{\text{OVD}}$	–	70	200	$\mu\text{s}$
Overvoltage Detection Release Time	$t_{\text{OVD\_R}}$	$V_{\text{DD}} < (V_{\text{OVD}} - V_{\text{OVD\_HYS}})$	–	3	–	$\mu\text{s}$
Rise Time	$t_{\text{R}}$	$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$	–	1	2.5	$\mu\text{s}$
Response Time	$t_{\text{RESP}}$	$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$	–	1.3	2.5	$\mu\text{s}$
Propagation Delay	$t_{\text{PD}}$	$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$	–	0.7	1.5	$\mu\text{s}$
Bandwidth	BW	$T_A = 25^\circ\text{C}$ , Small Signal $-3\text{ dB}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$	–	450	–	kHz
Noise Density	$N_{\text{D}}$	$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$ , 5 V variant	–	150	–	$\mu\text{A}/\sqrt{\text{Hz}}$
		$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$ , 3.3 V variant	–	230	–	$\mu\text{A}/\sqrt{\text{Hz}}$
Output Saturation Voltage	$V_{\text{SAT\_H}}$	$R_{\text{L\_VOUT}} = 10\text{ k}\Omega$ to GND	$V_{\text{DD}} - 0.25$	–	–	V
	$V_{\text{SAT\_L}}$	$R_{\text{L\_VOUT}} = 10\text{ k}\Omega$ to VDD	–	–	0.15	V
VOUT Short-Circuit Current	$I_{\text{SC\_VOUT}}$	$T_A = 25^\circ\text{C}$ , VOUT shorted to GND	–	25	–	mA
		$T_A = 25^\circ\text{C}$ , VOUT shorted to VDD	–	–25	–	mA
Common Mode Field Sensitivity	CMFS		–	4	–	mA/G

Continued on next page...

**COMMON ELECTRICAL CHARACTERISTICS (continued):** Valid over full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $150^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 100\text{ nF}$ , and  $V_{\text{DD}} = 5\text{ V}$  or  $3.3\text{ V}$ , unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>REFERENCE OUTPUT CHARACTERISTICS (VREF)</b>						
VREF Resistive Load	$R_{\text{L\_VREF}}$	VREF to GND or VREF to VDD	10	–	–	k $\Omega$
VREF Capacitive Load	$C_{\text{L\_VREF}}$	VREF to GND	–	1	6	nF
VREF Short-Circuit Current	$I_{\text{SC\_VREF}}$	VREF shorted to GND	–	25	–	mA
		VREF shorted to VDD	–	–25	–	mA

[1] Only enabled on 5 V devices.

**ACS37010LLZATR-050B5 PERFORMANCE CHARACTERISTICS:** Valid over full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $150^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 100\text{ nF}$ , and  $V_{\text{DD}} = 5\text{ V}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ. <sup>[1]</sup>	Max.	Units
<b>NOMINAL PERFORMANCE</b>						
Current Sensing Range	$I_{\text{PR}}$		-50	-	50	A
Sensitivity	Sens	$I_{\text{PR}(\text{min})} < I_{\text{P}} < I_{\text{PR}(\text{max})}$	-	40	-	mV/A
Quiescent Voltage Output	$V_{\text{QVO}}$	$I_{\text{P}} = 0\text{ A}$	-	2.5	-	V
Reference Voltage Output	$V_{\text{REF}}$		-	2.5	-	V
<b>ERROR COMPONENTS <sup>[1]</sup></b>						
Sensitivity Error	$E_{\text{SENS}}$	$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-1.5	$\pm 1.1$	1.5	%
		$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-1.5	$\pm 1.1$	1.5	%
Quiescent Voltage Output Error	$V_{\text{QVO\_E}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-8	$\pm 5$	8	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-8	$\pm 5$	8	mV
Reference Voltage Output Error	$V_{\text{REF\_E}}$	$T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-8	$\pm 5$	8	mV
		$T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-8	$\pm 5$	8	mV
Offset Error	$V_{\text{OE}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-4	$\pm 2$	4	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-4	$\pm 2$	4	mV
Noise	N	$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$ , $\text{BW} = 450\text{ kHz}$	-	5	-	mV <sub>RMS</sub>
Power Supply Sensitivity Error	$E_{\text{SENS\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-1.2	$\pm 0.8$	1.2	%
Power Supply Quiescent Voltage Output Error	$V_{\text{QVO\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-9	$\pm 6$	9	mV
Power Supply Reference Voltage Output Error	$V_{\text{REF\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-9	$\pm 6$	9	mV
Power Supply Offset Error	$V_{\text{OE\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-8	$\pm 5$	8	mV
<b>ERROR COMPONENTS INCLUDING LIFETIME DRIFT <sup>[2]</sup></b>						
Sensitivity Error Including Lifetime Drift	$E_{\text{SENS\_LTD}}$	$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-3	-	3	%
		$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-3.5	-	3.5	%
Quiescent Voltage Output Error Including Lifetime Drift	$V_{\text{QVO\_LTD}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-15	-	15	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-15	-	15	mV
Reference Voltage Output Error Including Lifetime Drift	$V_{\text{REF\_LTD}}$	$T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-15	-	15	mV
		$T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-15	-	15	mV
Offset Error Including Lifetime Drift	$V_{\text{OE\_LTD}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-3	-	3	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-3	-	3	mV

<sup>[1]</sup> Typical values are the mean  $\pm 3$  sigma of production distributions.

<sup>[2]</sup> Lifetime drift minimum/maximum values are  $\pm 3$  sigma, and are based on a statistical combination of production distributions and worst-case drift distributions observed after AEC-Q100 qualification stresses.

**ACS37010LLZATR-050B3 PERFORMANCE CHARACTERISTICS:** Valid over full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $150^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 100\text{ nF}$ , and  $V_{\text{DD}} = 3.3\text{ V}$ , unless otherwise specified

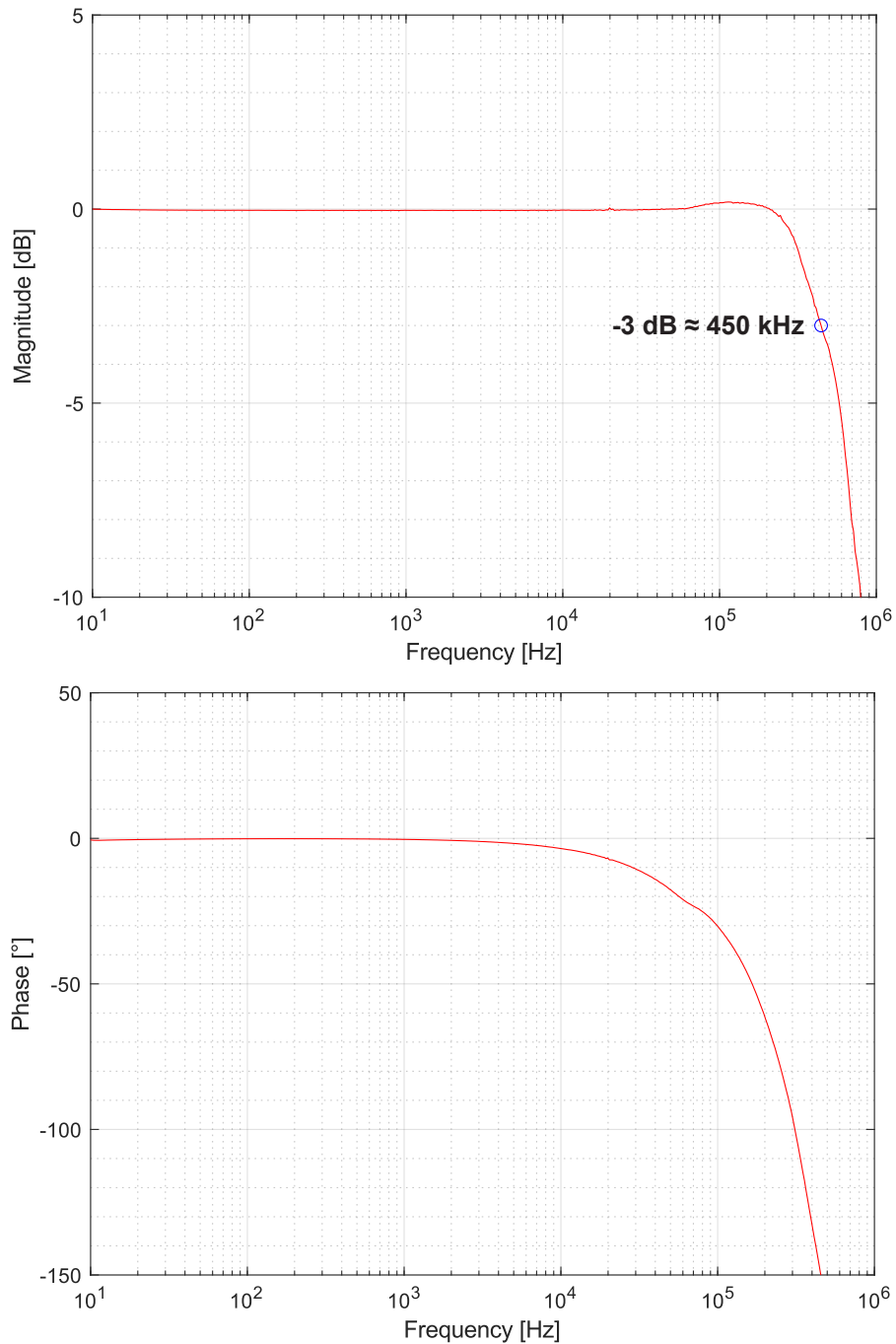
Characteristic	Symbol	Test Conditions	Min.	Typ. <sup>[1]</sup>	Max.	Units
<b>NOMINAL PERFORMANCE</b>						
Current Sensing Range	$I_{\text{PR}}$		-50	-	50	A
Sensitivity	Sens	$I_{\text{PR}(\text{min})} < I_{\text{P}} < I_{\text{PR}(\text{max})}$	-	26.4	-	mV/A
Quiescent Voltage Output	$V_{\text{QVO}}$	$I_{\text{P}} = 0\text{ A}$	-	1.65	-	V
Reference Voltage Output	$V_{\text{REF}}$		-	1.65	-	V
<b>ERROR COMPONENTS [1]</b>						
Sensitivity Error	$E_{\text{SENS}}$	$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-1.5	$\pm 1.1$	1.5	%
		$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-1.5	$\pm 1$	1.5	%
Quiescent Voltage Output Error	$V_{\text{QVO\_E}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-8	$\pm 4$	8	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-8	$\pm 4$	8	mV
Reference Voltage Output Error	$V_{\text{REF\_E}}$	$T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-8	$\pm 4$	8	mV
		$T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-8	$\pm 4$	8	mV
Offset Error	$V_{\text{OE}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-3	$\pm 1.5$	3	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-3	$\pm 1.5$	3	mV
Noise	N	$T_A = 25^\circ\text{C}$ , $C_{\text{L\_VOUT}} = 6\text{ nF}$ , $C_{\text{BYPASS}} = 1\text{ }\mu\text{F}$ , $\text{BW} = 450\text{ kHz}$	-	5	-	mV <sub>RMS</sub>
Power Supply Sensitivity Error	$E_{\text{SENS\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-1.4	$\pm 1.1$	1.4	%
Power Supply Quiescent Voltage Output Error	$V_{\text{QVO\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-6	$\pm 3$	6	mV
Power Supply Reference Voltage Output Error	$V_{\text{REF\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-6	$\pm 3$	6	mV
Power Supply Offset Error	$V_{\text{OE\_PS}}$	$V_{\text{DD}(\text{MIN})}$ to $V_{\text{DD}(\text{MAX})}$	-6	$\pm 3$	6	mV
<b>ERROR COMPONENTS INCLUDING LIFETIME DRIFT [2]</b>						
Sensitivity Error Including Lifetime Drift	$E_{\text{SENS\_LTD}}$	$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-2.5	-	2.5	%
		$I_{\text{P}} = 0.5 \times I_{\text{PR}(\text{max})}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-3.5	-	3.5	%
Quiescent Voltage Output Error Including Lifetime Drift	$V_{\text{QVO\_LTD}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-13	-	13	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-13	-	13	mV
Reference Voltage Output Error Including Lifetime Drift	$V_{\text{REF\_LTD}}$	$T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-13	-	13	mV
		$T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-13	-	13	mV
Offset Error Including Lifetime Drift	$V_{\text{OE\_LTD}}$	$I_{\text{P}} = 0\text{ A}$ , $T_A = 25^\circ\text{C}$ to $150^\circ\text{C}$	-3	-	3	mV
		$I_{\text{P}} = 0\text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	-3	-	3	mV

[1] Typical values are the mean  $\pm 3$  sigma of production distributions.

[2] Lifetime drift minimum/maximum values are  $\pm 3$  sigma, and are based on a statistical combination of production distributions and worst-case drift distributions observed after AEC-Q100 qualification stresses.



### CHARACTERISTIC PERFORMANCE ACS37010 TYPICAL FREQUENCY RESPONSE



### RESPONSE CHARACTERISTICS DEFINITIONS AND TYPICAL PERFORMANCE DATA

#### Response Time ( $t_{\text{RESPONSE}}$ )

The time interval between a) when the sensed input current reaches 90% of its final value, and b) when the sensor output reaches 90% of its full-scale value.

#### Propagation Delay ( $t_{\text{pd}}$ )

The time interval between a) when the sensed input current reaches 20% of its full-scale value, and b) when the sensor output reaches 20% of its full-scale value.

#### Rise Time ( $t_r$ )

The time interval between a) when the sensor reaches 10% of its full-scale value, and b) when it reaches 90% of its full-scale value.

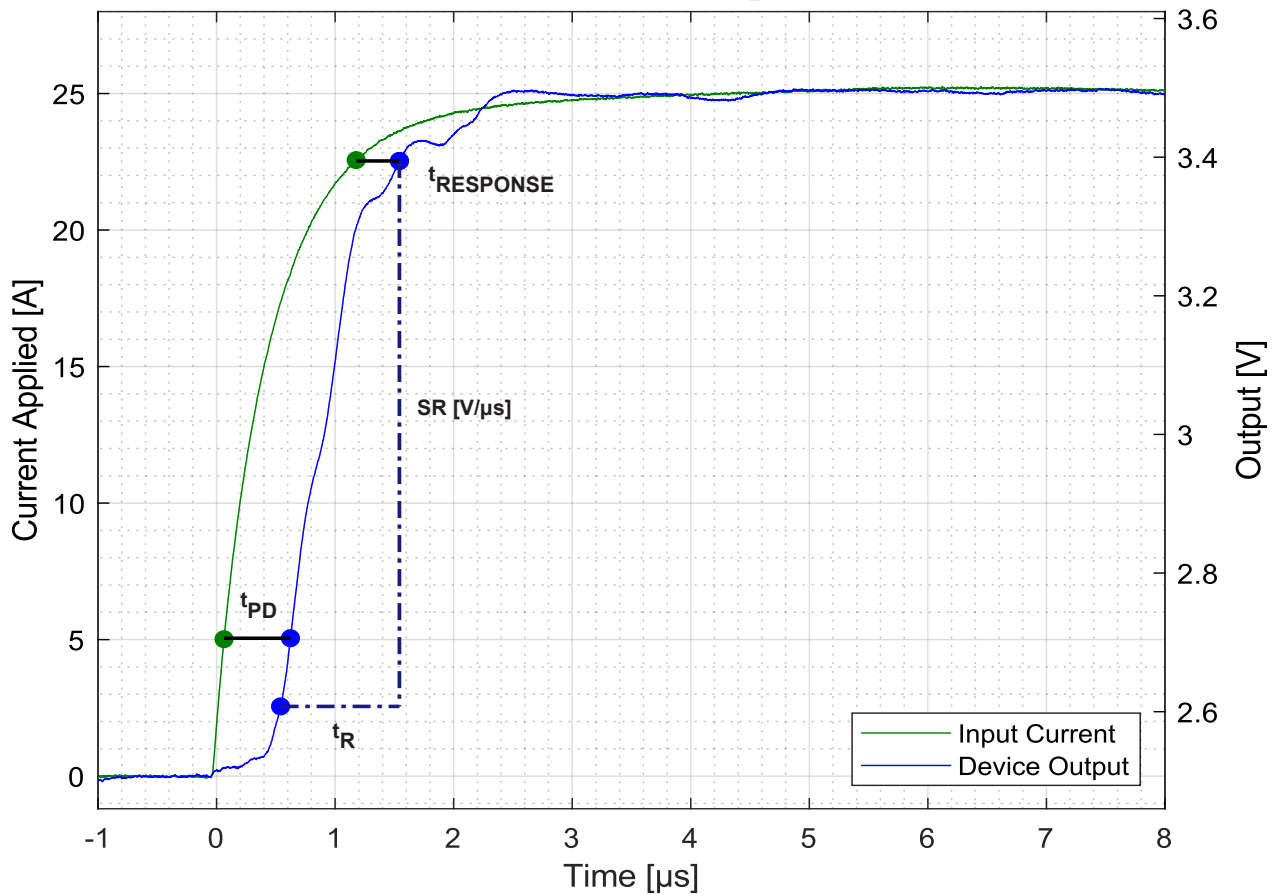
#### Output Slew Rate (SR)

The rate of change [ $\text{V}/\mu\text{s}$ ] in the output voltage from a) when the sensor reaches 10% of its full-scale value, and b) when it reaches 90% of its full-scale value.

#### Response Time, Propagation Delay, Rise Time, and Output Slew Rate

Applied current step with 10% to 90% rise time = 1  $\mu\text{s}$

Test Conditions:  $T_A = 25^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 1 \mu\text{F}$ ,  $C_{\text{L\_VOUT}} = 6 \text{ nF}$



## FUNCTIONAL DESCRIPTION OF POWER ON/OFF OPERATION

## Introduction

To ensure that the device output is reporting accurately, the ACS37010 contains an overvoltage and an undervoltage detection flag. This internal flag on  $V_{OUT}$  can be used to alert the system when the supply voltage for the device is outside of the operational range by putting the output into a known high-impedance (high Z) state. UVD is only active on 5 V devices.

The provided graphs in this section show  $V_{OUT}$  moving with  $V_{DD}$ . The voltage of  $V_{OUT}$  during a high-impedance state will be most consistent with a known load ( $R_{L\_VOUT}$ ,  $C_{L\_VOUT}$ ). Figure 3, Figure 4, Figure 5, Figure 6, Figure 7, and Figure 8 all use the same labeling scheme for different power thresholds. References in brackets “[ ]” are valid for each of these plots.

## POWER-ON OPERATION

## UVD Enabled

When UVD is enabled, as  $V_{DD}$  ramps up, the ACS37010  $V_{OUT}$  and  $V_{REF}$  pins are high Z until  $V_{DD}$  reaches and passes  $V_{UVD}$  [2]. Once  $V_{DD}$  passes [2], the device takes some time without  $V_{DD}$  dropping below  $V_{POR} - V_{POR\_HYS}$  [8] before the device enters normal operation.

## UVD Disabled

When UVD is disabled, as  $V_{DD}$  ramps up, the ACS37010  $V_{OUT}$  and  $V_{REF}$  pins are high Z until  $V_{DD}$  reaches and passes  $V_{POR}$  [1]. Once  $V_{DD}$  has passed  $V_{POR}$  [1],  $V_{OUT}$  enters normal operation.

## POWER-OFF OPERATION

## UVD Enabled

When UVD is enabled, before the device powers off, it will force  $V_{OUT}$  to GND if  $V_{DD}$  reaches less than  $V_{UVD} - V_{UVD\_HYS}$  [6]. When  $V_{POR} - V_{POR\_HYS}$  [8] is reached,  $V_{OUT}$  and  $V_{REF}$  will go high Z.

## UVD Disabled

When UVD is disabled,  $V_{REF}$  and  $V_{OUT}$  continue to report until  $V_{DD}$  is less than  $V_{POR} - V_{POR\_HYS}$  [8], at which point,  $V_{OUT}$  and  $V_{REF}$  will enter a high Z state.

NOTE: Because the device is entering a high Z state and not driving the output, the time it takes the output to reach a steady state will depend on the external circuitry used.

## Voltage Thresholds

POWER-ON RESET RELEASE VOLTAGE ( $V_{POR}$ )

If  $V_{DD}$  falls below  $V_{POR} - V_{POR\_HYS}$  [8] while in operation, the digital circuitry turns off and the output will re-enter a high Z state. After  $V_{DD}$  recovers and exceeds  $V_{UVD}$  [2], the output will begin reporting again after the delay of  $t_{PO}$ .

UNDERVOLTAGE DETECTION THRESHOLD ( $V_{UVD}$ )

The 5 V devices are factory-programmed with UVD enabled. It is important to note that, when powering up the device for the first time after a Power-On Reset event,  $V_{OUT}$  and  $V_{REF}$  will remain high Z until  $V_{DD}$  is raised above  $V_{UVD}$  [2], at which point the  $V_{OUT}$  and  $V_{REF}$  outputs will begin to resume normal operation. If UVD is disabled or it is a 3.3 V device,  $V_{OUT}$  and  $V_{REF}$  will begin normal operation after  $V_{DD}$  raises above  $V_{POR}$  [1] under the same conditions.

If  $V_{DD}$  drops below  $V_{UVD} - V_{UVD\_HYS}$  [6] after normal operation,  $V_{OUT}$  will pull to GND regardless of  $R_{L\_VOUT}$  configuration. The  $V_{OUT}$  will remain at GND until  $V_{DD}$  raises above  $V_{UVD}$  [7] or  $V_{DD}$  falls below  $V_{POR} - V_{POR\_HYS}$  [8]. If  $V_{DD}$  rises above  $V_{UVD}$  [7] after a UVD event, the  $V_{OUT}$  and  $V_{REF}$  outputs will resume operation. If  $V_{DD}$  drops below  $V_{POR} - V_{POR\_HYS}$  [8], the device will enter a POR event and reset;  $V_{OUT}$  and  $V_{REF}$  will switch to high Z if this occurs.

OVERVOLTAGE DETECTION THRESHOLD ( $V_{OVD}$ )

When  $V_{DD}$  raises above  $V_{OVD}$  [4], the output of the  $V_{OUT}$  pin will go high Z,  $V_{REF}$  be pulled to GND, and  $V_{OUT}$  will be pulled to either VDD or GND, depending on the configuration (pull-up vs. pull-down) of  $R_{L\_VOUT}$ .

OVERVOLTAGE/UNDERVOLTAGE DETECTION  
HYSTERESIS ( $V_{OVD\_HYS}$ ,  $V_{UVD\_HYS}$ )

There is hysteresis between enable and disable thresholds to reduce nuisance flagging and clears. These are represented in Figure 8 between the relevant thresholds.

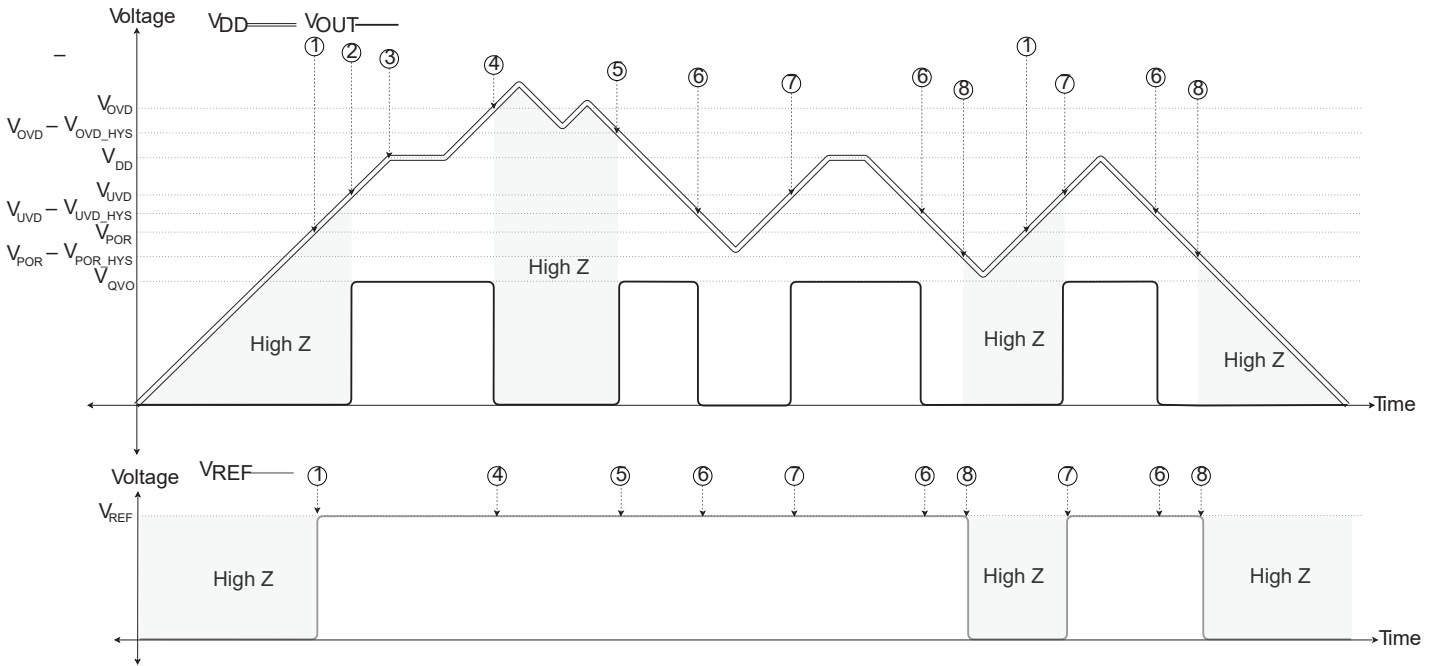


Figure 3: Power States Thresholds with  $V_{OUT}$  Behavior for a 5 V Device,  $R_{L\_VOUT}$  = Pull-Down, UVD Enabled

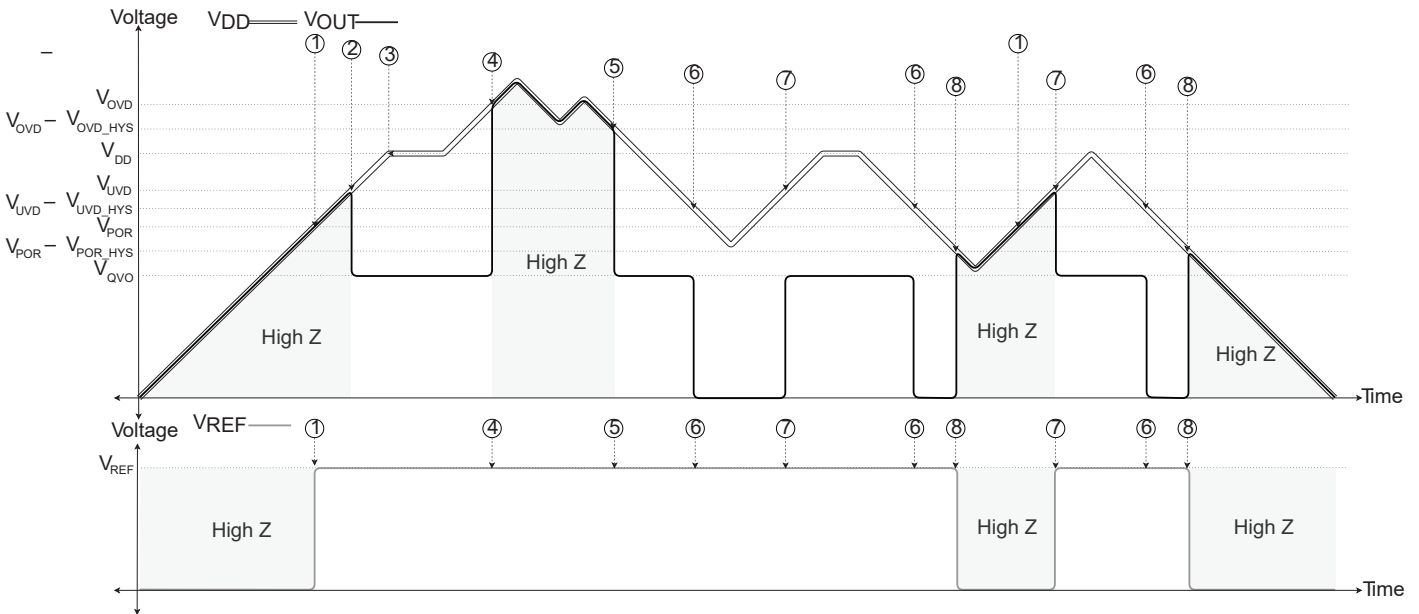


Figure 4: Power States Thresholds with  $V_{OUT}$  and  $V_{REF}$  Behavior, 5 V Device,  $R_{L\_VOUT}$  = Pull-Up, UVD Enabled

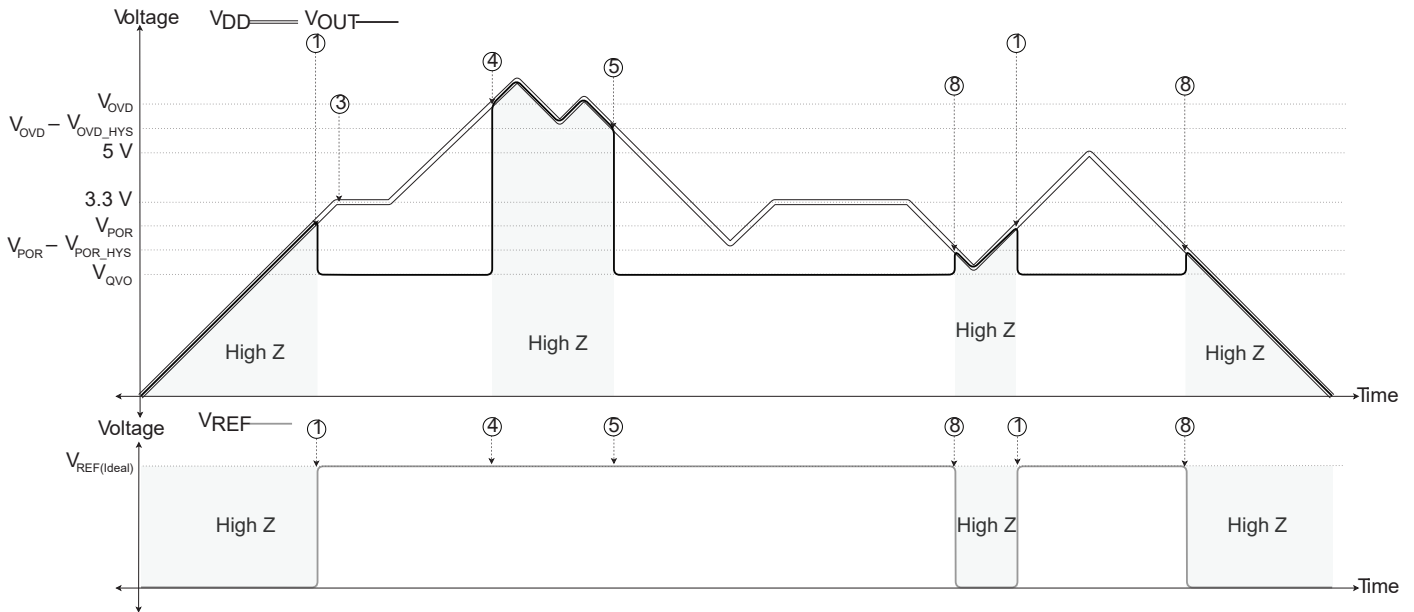


Figure 5: Power States Thresholds with  $V_{OUT}$  and  $V_{REF}$  Behavior, 3.3 V Device,  $R_L$  = Pull-Up, UVD Disabled

### Timing Thresholds

#### POWER-ON DELAY ( $t_{PO}$ )

When the supply is ramped to  $V_{UVD}$  [2], the device will require a finite time to power its internal components before the outputs are released from high Z and can respond to an input magnetic field. Power-On Time,  $t_{PO}$ , is defined as the time it takes for the output voltage to settle within  $\pm 10\%$  of its steady-state value under an applied magnetic field, which can be seen as the time from [2] to [A] in Figure 6. After this delay, the output will quickly approach  $V_{OUT(IP)} = Sens \times I_P + V_{REF}$ .

#### OVERVOLTAGE AND UNDERVOLTAGE DETECTION TIME AND DETECTION RELEASE TIME

( $t_{OVD}/t_{OVD\_R}$ ,  $t_{UVD}/t_{UVD\_R}$ )

The enable time for OVD,  $t_{OVD}$ , is the time from  $V_{OVD}$  [4] to OVD flag [B]. The UVD enable time,  $t_{UVD}$ , is the time from  $V_{UVD} - V_{UVD\_HYS}$  [6] to the UVD flag [D].

If  $V_{DD}$  ramps from  $>V_{UVD} - V_{UVD\_HYS}$  [6] to  $<V_{POR} - V_{POR\_HYS}$  [8] faster than  $t_{UVD}$ , then the device will not have time to report a UVD event before power off occurs.

The detection release time for OVD,  $t_{OVD\_R}$ , is the time from  $V_{OVD} - V_{OVD\_HYS}$  [5] to the OVD clear to normal operation [C]. The UVD disable time,  $t_{UVD\_R}$ , is the time from  $V_{UVD}$  [7] to the point that the UVD flag clears and  $V_{OUT}$  returns to nominal operation [E]. The disable time does not have a counter for either OVD or UVD to release the output and resume reporting.

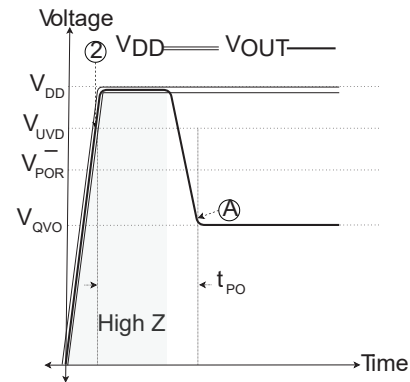


Figure 6:  $t_{PO}$  behavior UVD enabled,  $R_{L\_VOUT} = \text{Pull-Up}$

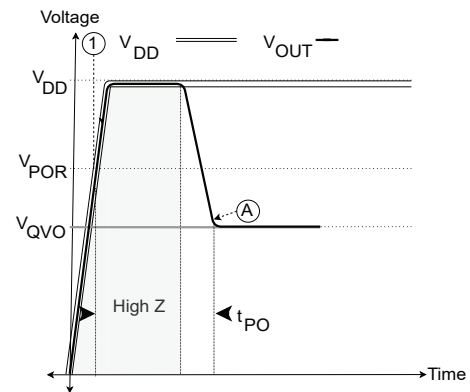


Figure 7:  $t_{PO}$  behavior UVD disabled,  $R_{L\_VOUT} = \text{Pull-Up}$

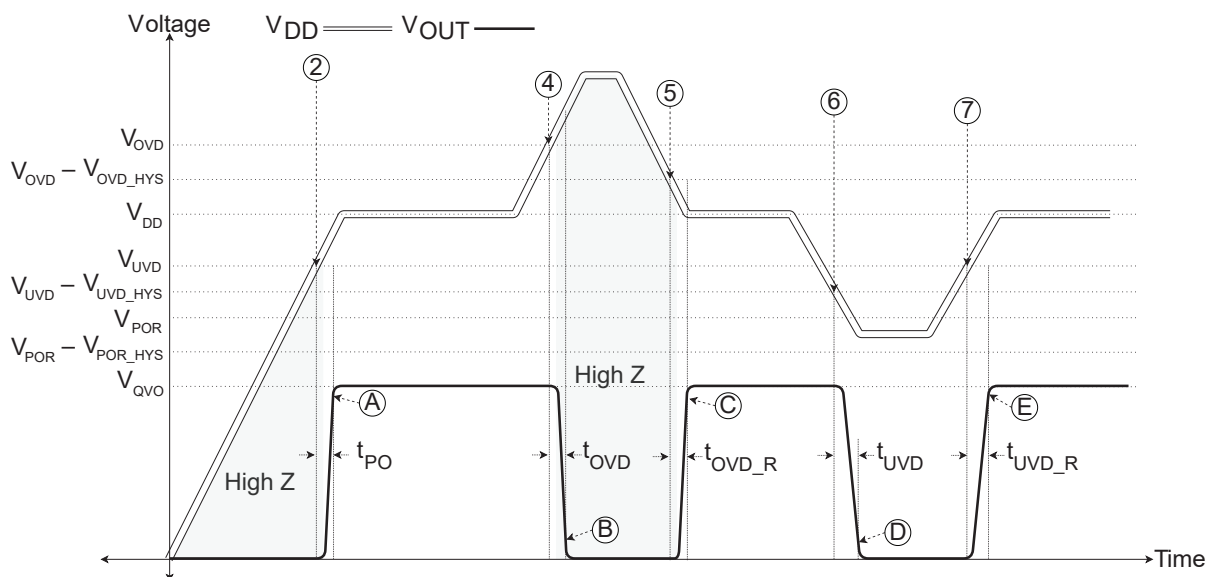


Figure 8:  $t_{PO}$ , and  $t_{OVD}/t_{OVD\_R}$ , and  $t_{UVD}/t_{UVD\_R}$  with  $R_{L\_VOUT} = \text{Pull-Up}$

## DEFINITIONS OF OPERATING AND PERFORMANCE CHARACTERISTICS

**Quiescent Voltage Output ( $V_{QVO}$ )**

Quiescent Voltage Output, or  $V_{QVO}$ , is defined as the voltage on the output,  $V_{OUT}$ , when zero amps are applied through  $I_P$ .

**Quiescent Voltage Output Error ( $V_{QVO\_E}$ )**

Quiescent Voltage Output Error, or  $V_{QVO\_E}$ , is defined as the drift of  $V_{QVO}$  from room to hot or room to cold (25°C to 150°C or 25°C to -40°C, respectively). To improve overtemperature performance, the temperature drift is compensated with Allegro factory trim to remain within the limits across temperature.

**Reference Voltage Output ( $V_{REF}$ )**

The Reference Voltage Output, or  $V_{REF}$ , reports the quiescent voltage output for the output channel,  $V_{OUT}$ . The internally generated  $V_{REF}$  is used in a pseudo-differential mode to remove errors due to the reference shifts or noise on the ground line.

**Reference Voltage Temperature Drift ( $V_{REF\_E}$ )**

Reference Voltage Output Error, or  $V_{REF\_E}$ , is defined as the drift of  $V_{REF}$  from room to hot or room to cold (25°C to 150°C or 25°C to -40°C, respectively).

**Offset Error ( $V_{OE}$ )**

Offset Error, or  $V_{OE}$ , is defined as the difference between  $V_{QVO}$  and  $V_{REF}$ .  $V_{OE}$  includes  $V_{QVO\_E} - V_{REF}$  from room to hot or room to cold (25°C to 150°C or 25°C to -40°C, respectively).

**Output Saturation Voltage ( $V_{SAT\_H}$  /  $V_{SAT\_L}$ )**

Output Saturation Voltage, or  $V_{SAT}$ , is defined as the voltage that the  $V_{OUT}$  does not pass as a result of an increasing magnitude of current.  $V_{SAT\_H}$  is the highest voltage the output can drive to, while  $V_{SAT\_L}$  is the lowest. Note that changing the sensitivity does not change the  $V_{SAT}$  points.

**Sensitivity (Sens)**

Sensitivity, or Sens, is the ratio of the output swing versus the applied current through the primary conductor,  $I_P$ . This current causes a voltage deviation away from  $V_{QVO}$  on the  $V_{OUT}$  output until  $V_{SAT}$ . The magnitude and direction of the output voltage swing is proportional to the magnitude and direction of the applied current. This proportional relationship between output and input is Sensitivity and is defined as:

$$Sens = \frac{V_{OUT(IP_1)} - V_{OUT(IP_2)}}{IP_1 - IP_2}$$

where  $IP_1$  and  $IP_2$  are two different currents, and where  $V_{OUT(IP_1)}$  and  $V_{OUT(IP_2)}$  are the voltages of the device at those applied currents.

**Sensitivity Error ( $E_{SENS}$ )**

Sensitivity Error, or  $E_{SENS}$ , is the error of Sensitivity from room to hot or room to cold (25°C to 150°C or 25°C to -40°C, respectively). Sensitivity error is compensated with Allegro factory trim.

**Error Components Including Lifetime Drift ( $E_{SENS\_LTD}$  /  $V_{QVO\_LTD}$  /  $V_{REF\_LTD}$  /  $V_{OE\_LTD}$ )**

Lifetime drift characteristics are based on a statistical combination of production distributions and worst-case distribution of parametric drift of individuals observed during AEC-Q100 qualification. Solder reflow induces stress on the ACS37010 device causing parametric shifts and lifetime drift limits apply immediately after solder reflow as well as long term use.

**Power Supply Sensitivity Error ( $E_{SENS\_PS}$ )**

Power Supply Sensitivity Error, or  $E_{SENS\_PS}$ , is defined as the percent sensitivity error measured between  $V_{DD}$  and  $V_{DD} \pm 10\%$ . For a 5 V device, this is 5 to 4.5 V and 5 to 5.5 V. For a 3.3 V device, this is 3.3 to 3 V and 3.3 to 3.6 V.

**Power Supply Offset Error ( $V_{OE\_PS}$ )**

Power Supply Offset Error, or  $V_{OE\_PS}$ , is defined as the offset error in mV between  $V_{DD}$  and  $V_{CC} \pm 10\% V_{DD}$ . For a 5 V device, this is 5 to 4.5 V and 5 to 5.5 V. For a 3.3 V device, this is 3.3 to 3 V and 3.3 to 3.6 V.



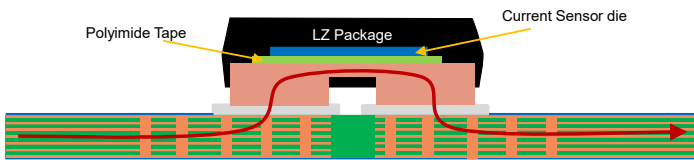
## THERMAL PERFORMANCE

### Thermal Rise vs. Primary Current

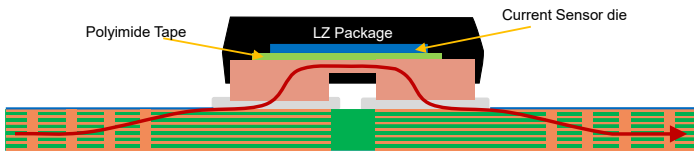
Self-heating due to the flow of current in the package IP conductor should be considered during the design of any current sensing system. The sensor, printed circuit board (PCB), and contacts to the PCB will generate heat and act as a heat sink as current moves through the system.

The thermal response is highly dependent on PCB layout, copper thickness, cooling techniques, and the profile of the injected current. The current profile includes peak current value, current “on-time”, and duty cycle.

Placing vias under the copper pads of the Allegro current sensor evaluation board minimizes the current path resistance and improves heatsinking to the PCB, while vias outside of the pads limit the current path to the top of the PCB trace and have worse heatsinking under the part (see Figure 9 and Figure 10).

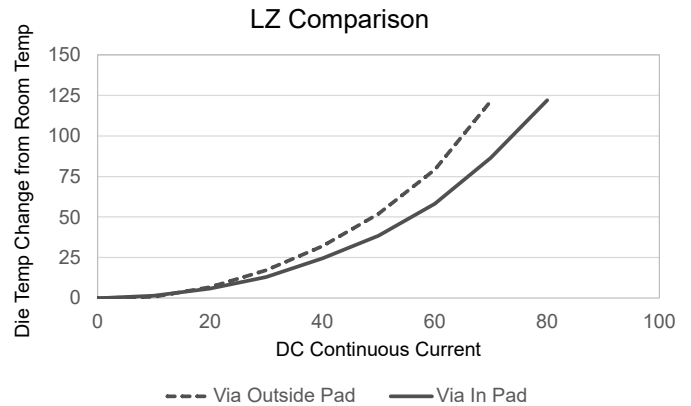


**Figure 9: Vias Under Copper Pads, LZ Package**



**Figure 10: No Vias Under Copper Pads, LZ Package**

The plot in Figure 11 shows the measured rise in steady-state die temperature of the ACS37010 versus DC continuous current at an ambient temperature,  $T_A$ , of 25°C for two board designs: filled vias under copper pads and no vias under copper pads. Note the thermal offset curves may be directly applied to other values of  $T_A$ . Using in-pad vias has better thermal performance than no in-pad vias.

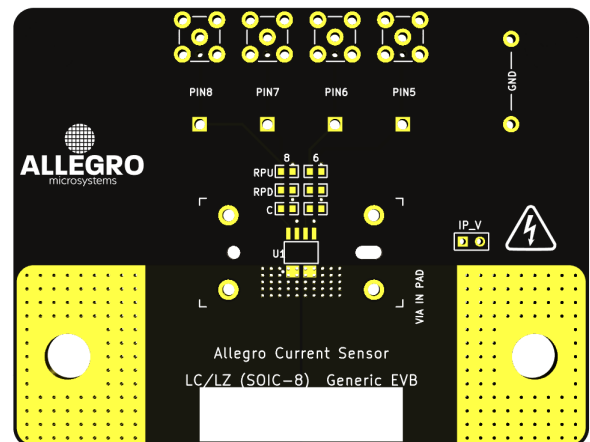


**Figure 11: LZ Package Comparison with and without In-Pad Vias**

The thermal capacity of the ACS37010 should be verified by the end user in the application’s specific conditions. The maximum junction temperature,  $T_{J(max)}$  (165°C), should not be exceeded. Measuring the temperature of the top of the package is a close approximation of the die temperature.

### Evaluation Board Layout

Thermal data shown in Figure 11 was collected using the ASEK37010 Evaluation Board (TED-0004110, LC/LZ Current Sensor Evaluation Board). This board includes six layers. The ASEK37010 evaluation board is shown in Figure 12.



**Figure 12: LZ Package Allegro Evaluation Board**

Gerber files for the ASEK37010 evaluation board are available for download from the Allegro website. See the technical documents section of the ACS37010 webpage.



## PACKAGE OUTLINE DRAWING

For Reference Only – Not for Tooling Use

(Reference DWG-0000385, Rev. 1)

PRELIMINARY

NOT TO SCALE

Dimensions in millimeters

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions  
Exact case and lead configuration at supplier discretion within limits shown

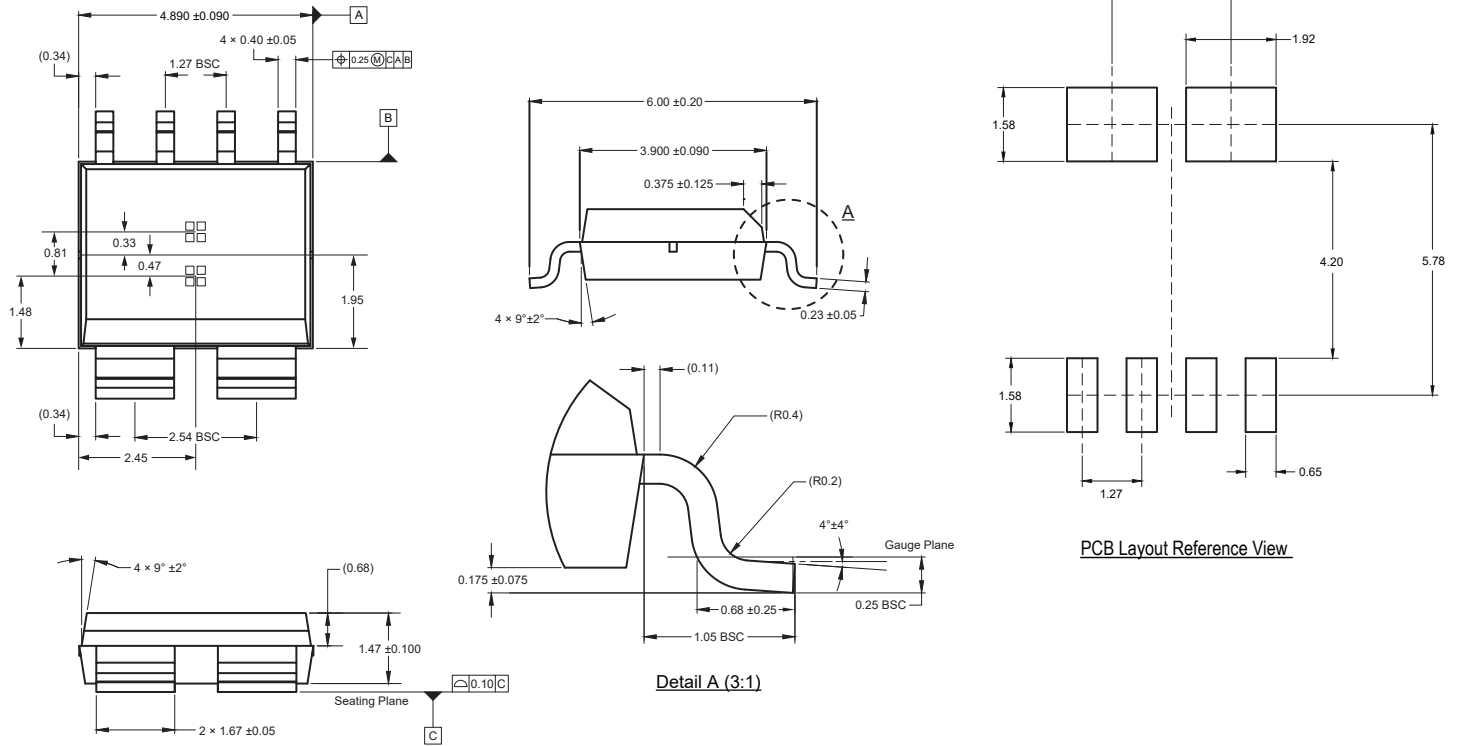


Figure 13: Custom 6-Pin SOIC (Suffix LZ)

### Revision History

Number	Date	Description
–	March 13, 2023	Initial release
1	March 29, 2023	Updated Error Components Including Lifetime Drift sections of Performance Characteristic tables (Pages 7, 8)

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